

10 9 8 7 6 5 4 3 2 1

F

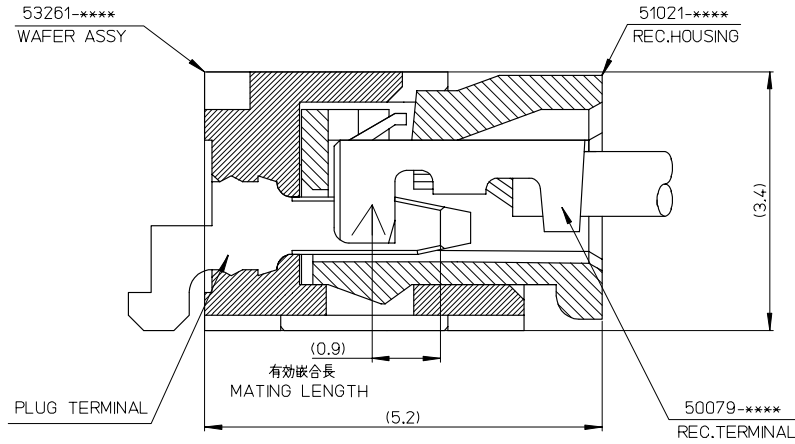
E

D

C

B

A



53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: YAOYAGI CHKD: YMAEDA APPR: NUKITA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY Y. AOYAGI	DATE 2006/01/30	TITLE 1.25 W-T-O-B CONN. 51021,53261 MATING CROSS SECTION		
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED		
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	DOCUMENT NO. SD-51021-002		
	ANGULAR	± --- °	MATERIAL NO. SEE CHART		SHEET NO. 1 OF 1		
0	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

fb_frame_A3_1_ME_S
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9

8

7

6

5

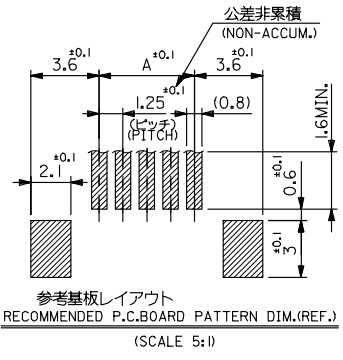
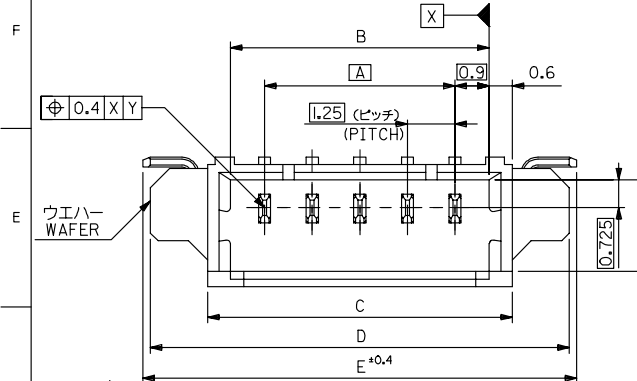
4

3

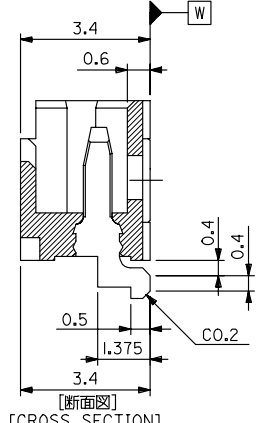
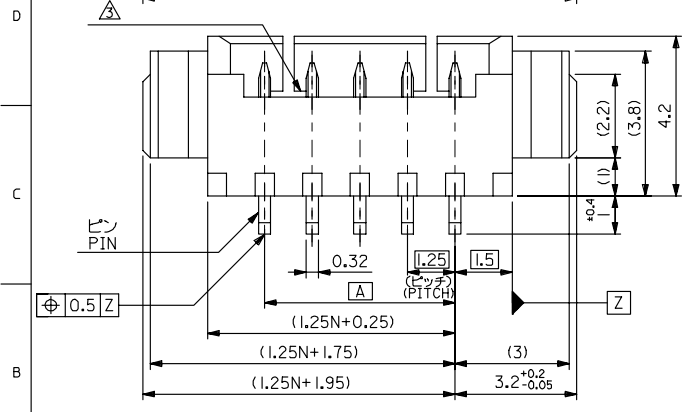
2

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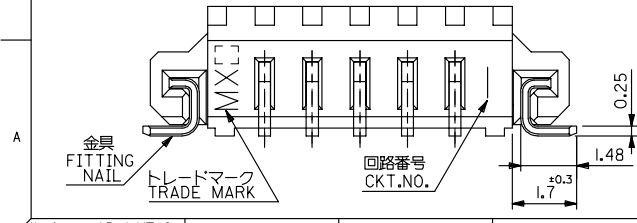
10 9 8 7 6 5 4 3 2 1



- 注記 NOTES**
1. 嵌合相手: 51021シリーズ
MATES WITH: 51021 SERIES
 2. 材質 MATERIAL
ウエハー: NYLON46,UL94V-0
ピン: リン青銅, 半田メッキ
PIN: PHOS-BRO., Sn-Pb(9:1) 3 μmMIN. OVER Cu 1 μmMIN. PLATING
金具: リン青銅, 半田メッキ
FITTING NAIL: PHOS-BRO., Sn-Pb(9:1) 2 μmMIN. OVER Cu 1 μmMIN. PLATING
 3. ロック窓は2、3極は1箇所、4極以上は2箇所とする。
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CKT. AND TWO PLACES FOR MORE THAN 3 CKT.
 4. ソルダータール部のスレ量及び金具(補強板)のスレ量は基準面[W]に対し、上方向0.05 MAX.、下方向に0.1 MAX.とする。
OFFSET BETWEEN BASIS PLANE [W] TO SOLDER TAIL BOTTOM: UPPER SIDE: 0.05MAX. LOWER SIDE: 0.1MAX.



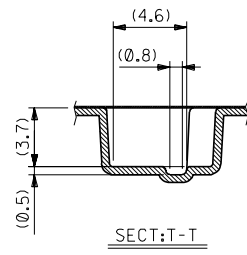
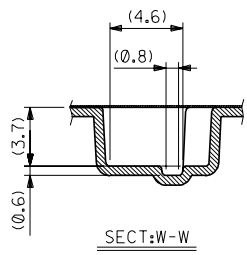
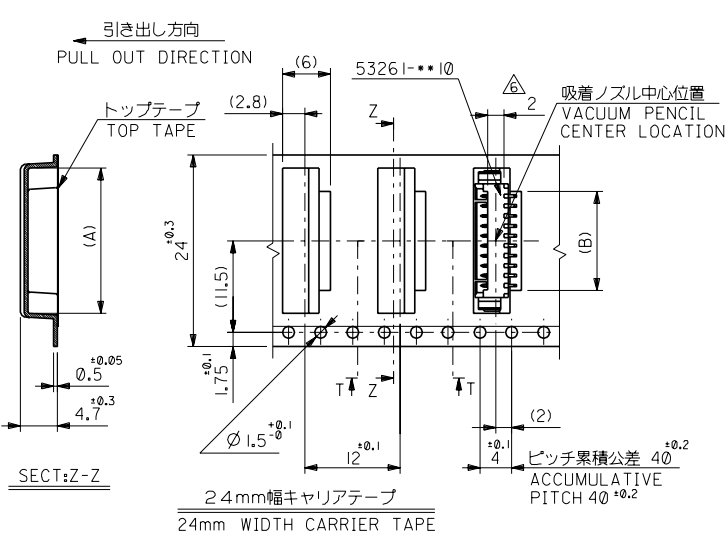
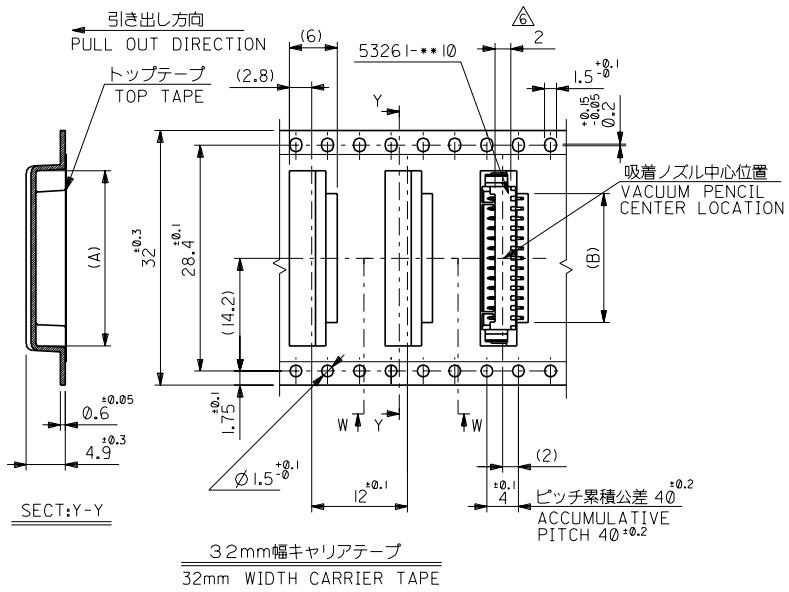
23.9	23.5	20.5	19.3	17.5	53261-1510	15
22.65	22.25	19.25	18.05	16.25	-1410	14
21.4	21	18	16.8	15	-1310	13
20.15	19.75	16.75	15.55	13.75	-1210	12
18.9	18.5	15.5	14.3	12.5	-1110	11
17.65	17.25	14.25	13.05	11.25	-1010	10
16.4	16	13	11.8	10	-0910	9
15.15	14.75	11.75	10.55	8.75	-0810	8
13.9	13.5	10.5	9.3	7.5	-0710	7
12.65	12.25	9.25	8.05	6.25	-0610	6
11.4	11	8	6.8	5	-0510	5
10.15	9.75	6.75	5.55	3.75	-0410	4
8.9	8.5	5.5	4.3	2.5	-0310	3
7.65	7.25	4.25	3.05	1.25	53261-0210	2
E	D	C	B	A	ENG. NO.	極数 CKT.



REVISED IEC NO. J2005-1631 2004/12/02 DRW: NESUZUKI CHK: KATOYODA APPR: NIKITA 2004/12/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HSEK INE		DATE 89/10/18		
	10 OVER 30 UNDER	±0.25	CHECKED BY HHIRAMOT		DATE 94/06/23		
	30 OVER	±0.3	APPROVED BY MFUKUSHI		DATE 94/06/23		
ANGULAR ±3°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE DRAWING		MOLEX INCORPORATED	
SIZE A3				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DOCUMENT NO. SD-53261-**10					SHEET NO. 1 OF 1		

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DWG. NO. SD-53261-090



32	32.4	16.2	22	53261-1390	13	
		14.95	20.75	-1290	12	
		13.7	19.5	-1190	11	
		12.45	18.25	-1090	10	
24	24.4	11.2	17	-0990	9	
		9.95	15.75	-0890	8	
		8.7	14.5	-0790	7	
		7.45	13.25	-0690	6	
		6.2	12	-0590	5	
		4.95	10.75	53261-0490	4	
キャリアテープ幅 CARRIER TAPE WIDTH		C	B	A	ENG. NO.	種数 CKT.

材料 MATERIAL		注記参照 SEE NOTES		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
仕上げ FINISH		—		REVISE ONLY ON CAD SYSTEM	
適用電線範囲 WIRE RANGE		—		TITLE 名称 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT. EMBOSSED TAPE PACKAGE	
被覆外径 INS. RANGE		—		DWG. NO. SHEET 2 OF 3 REV SD-53261-090 F	
角度 ANGLE	±3°	記号 LTR	変更内容 REVISION RECORD	DATE	DR. CHK.
30°以上 OVER	±0.3	F	変更 REVISED (02/20/01)	00/12/8	S.M. T.Y.
10°以上 未過 OVER 30 UNDER	±0.25	E	変更及び再作図 REVISED/REDRAWN (J30522)	93/6/1	K.T. H.H.
10°以下 UNDER	±0.2				
一般公差 GENERAL TOLERANCES					

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